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Standards

Irish Standard  
I.S. EN 16602-70-10:2015

# Space product assurance - Qualification of printed circuit boards

**I.S. EN 16602-70-10:2015**

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## Space product assurance - Qualification of printed circuit boards

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circuits imprimés

Raumfahrtproduktsicherung - Qualifizierung von  
Leiterplatten

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## Foreword

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This document (EN 16602-70-10:2015) has been prepared by Technical Committee CEN/CLC/TC 5 “Space”, the secretariat of which is held by DIN.

This standard (EN 16602-70-10:2015) originates from ECSS-Q-ST-70-10C.

This European Standard shall be given the status of a national standard, either by publication of an identical text or by endorsement, at the latest by July 2015, and conflicting national standards shall be withdrawn at the latest by July 2015.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CEN [and/or CENELEC] shall not be held responsible for identifying any or all such patent rights.

This document has been prepared under a mandate given to CEN by the European Commission and the European Free Trade Association.

This document has been developed to cover specifically space systems and has therefore precedence over any EN covering the same scope but with a wider domain of applicability (e.g. : aerospace).

According to the CEN-CENELEC Internal Regulations, the national standards organizations of the following countries are bound to implement this European Standard: Austria, Belgium, Bulgaria, Croatia, Cyprus, Czech Republic, Denmark, Estonia, Finland, Former Yugoslav Republic of Macedonia, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland, Turkey and the United Kingdom.

# 1 Scope

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This Standard defines the requirements for evaluation, qualification and maintenance of qualification of PCB manufacturers for different types of PCBs.

This Standard is applicable to the following type of PCBs:

- Rigid PCBs (single-sided, double-sided, multilayer, sequential-laminated multilayer, metal core)
- Flexible PCB (single-sided and double-sided)
- Rigid-flex PCBs (multilayer and sequential-laminated multilayer)
- High frequency PCBs
- Special PCBs.

PCBs are used for the mounting of components in order to produce PCB assemblies performing complex electrical functions. The PCBs are subjected to thermal and mechanical shocks during their assembly such as mounting of components by soldering, rework and repair under normal terrestrial conditions, and in addition the complex PCB assembly are subjected to the environment imposed by launch and space flights.

This standard may be tailored for the specific characteristics and constraints of a space project in conformance with ECSS-S-ST-00.

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